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COMPLEMENTARY 40V HIGH PERFORMANCE TRANSISTOR

Features

NPN Transistor

- BV_{CEO} > 40V
- I_C = 3A Continuous Collector Current
- Low Saturation Voltage (500mV max @ 1A)
- R_{SAT} = 195mΩ for a low equivalent On-Resistance

PNP Transistor

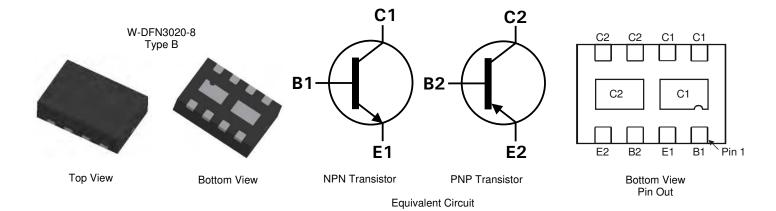
- BV_{CEO} > -40V
- I_C = -3A Continuous Collector Current
- Low Saturation Voltage (-500mV max @ -1A)
- R_{SAT} = 350mΩ for a low equivalent On-Resistance
- hFE characterized up to 2A for high current gain hold up
- Low profile 0.8mm high package for thin applications
- R_{0JA} efficient, 40% lower than SOT26
- 6mm² footprint, 50% smaller than TSOP6 and SOT26
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP capable (Note 4)

Mechanical Data

- Case: W-DFN3020-8 Type B
- Nominal package height: 0.8mm
- Case material: molded plastic. "Green" molding compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu, Solderable per MIL-STD-202, Method 208
- Weight: 0.013 grams (approximate)

Applications

- DC DC Converters
- · Charging circuits
- Power switches
- LED Backlighting circuits
- Motor control
- Portable applications



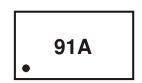
Ordering Information (Note 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC4591AMCTA	AEC-Q101	91A	7	8	3,000
ZXTC4591AMCQTA	Automotive	91A	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
- 5. For packaging details, go to our website at http://www.diodes.com

Marking Information



91A = Product type marking code Top view, dot denotes pin 1



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Parameter	Symbol	NPN	PNP	Unit		
Collector-Base Voltage		V_{CBO}	40	-40		
Collector-Emitter Voltage		V_{CEO}	40	-40	V	
Emitter-Base Voltage		V _{EBO}	7	-7		
Peak Pulse Current		Ісм	3	-3		
Continuous Collector Current (Notes 6 & 9) (Notes 7 & 9)		Ic	2	-1.5	Α	
			2.5	-2		
Base Current		Ι _Β	30	00	mA	

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	NPN	PNP	Unit	
	(Notes 6 & 9)		1.5 12 2.45 19.6 1.13 8		W mW/°C
Power Dissipation	(Notes 7 & 9)	Б			
Linear Derating Factor	(Notes 8 & 9)	P _D			
	(Notes 8 & 10)		1.7 13.6		
	(Notes 6 & 9)		83.3		
Thermal Resistance, Junction to Ambient	(Notes 7 & 9)		51	51.0	
Thermal Nesistance, Junction to Ambient	(Notes 8 & 9)	$R_{ hetaJA}$	11	1	°C/W
	(Notes 8 & 10)		73	73.5	
Thermal Resistance, Junction to Lead (Notes 9 & 11)		$R_{ heta JL}$	17	'.1	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150		°C	

Notes:

- 6. For a dual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half.

 7. Same as note (6), except the device is measured at t <5 sec.

 8. Same as note (6), except the device is surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper.

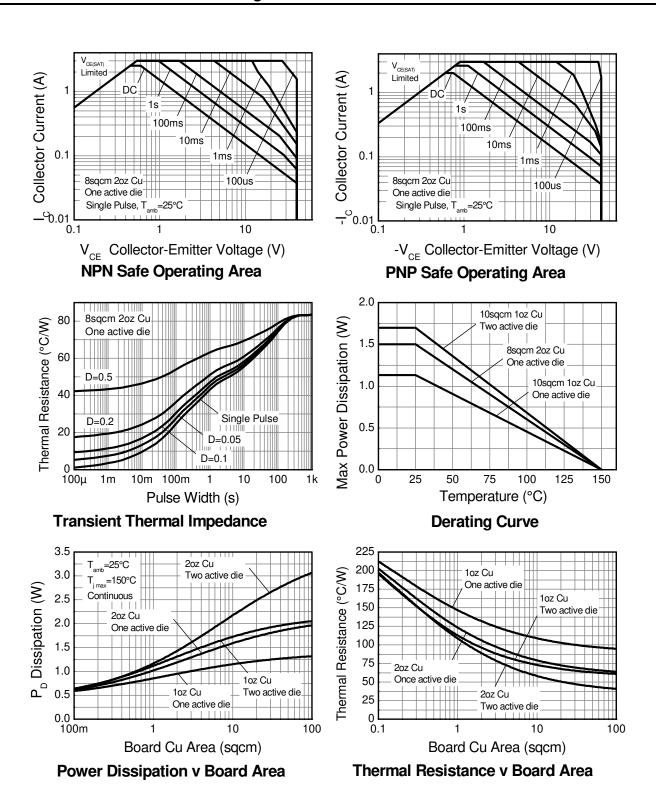
 9. For a dual device with one active die.

 10. For dual device with 2 active die running at equal power.

- 11. Thermal resistance from junction to solder-point (on the exposed collector pad).



Thermal Characteristics and Derating Information







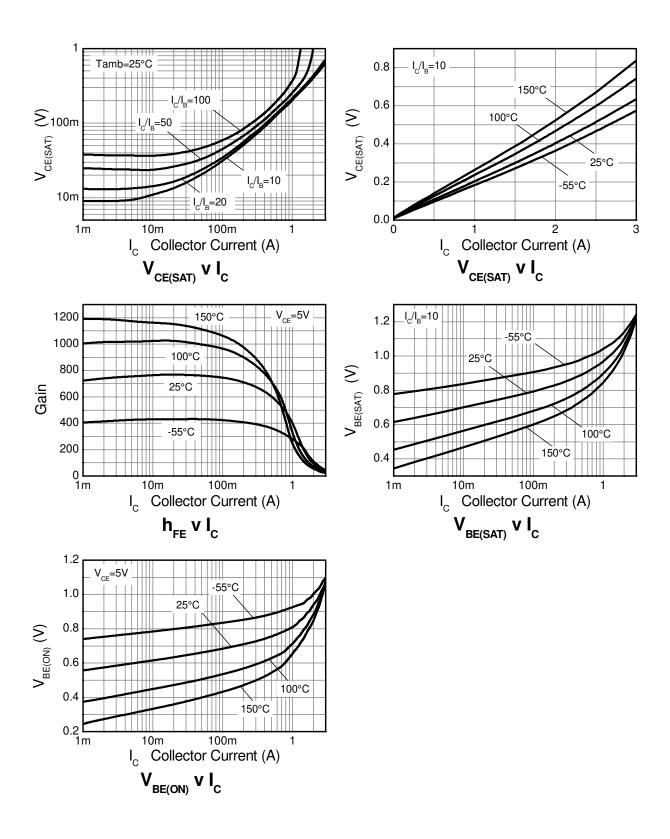
NPN - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_CBO	40	-	-	V	$I_C = 100\mu A$
Collector-Emitter Breakdown Voltage (Note 12)	BV_CEO	40	-	-	V	$I_C = 10mA$
Emitter-Base Breakdown Voltage	BV _{EBO}	7	-	-	V	I _E = 100μA
Collector Cutoff Current	I _{CBO}	-	-	100	nA	$V_{CB} = 30V$
Emitter Cutoff Current	I _{EBO}	-	-	100	. nA	$V_{EB} = 4V$
Collector Emitter Cutoff Current	I _{CES}	-	-	100	nA	V _{CE} = 30V
Static Forward Current Transfer Ratio (Note 12)	h _{FE}	300 300 200 35	- - -	- 900 - -	-	$\begin{split} I_{C} &= 1 \text{mA, V}_{CE} = 5 \text{V} \\ I_{C} &= 500 \text{mA, V}_{CE} = 5 \text{V} \\ I_{C} &= 1 \text{A, V}_{CE} = 5 \text{V} \\ I_{C} &= 2 \text{A, V}_{CE} = 5 \text{V} \end{split}$
Collector-Emitter Saturation Voltage (Note 12)	$V_{CE(sat)}$	-	-	300 500	mV	$I_C = 0.5A$, $I_B = 50mA$ $I_C = 1A$, $I_B = 100mA$
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	-	-	1.0	V	$I_C = 1A, V_{CE} = 5V$
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	-	-	1.1	V	$I_C = 1A$, $I_B = 100mA$
Output Capacitance	C_{obo}	-	-	10	pF	V _{CB} = 10V, f = 1MHz
Transition Frequency	fτ	150	-	-	MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz

Notes: 12. Measured under pulsed conditions. Pulse width $\leq 300 \mu s$. Duty cycle $\leq 2\%$.



NPN - Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)





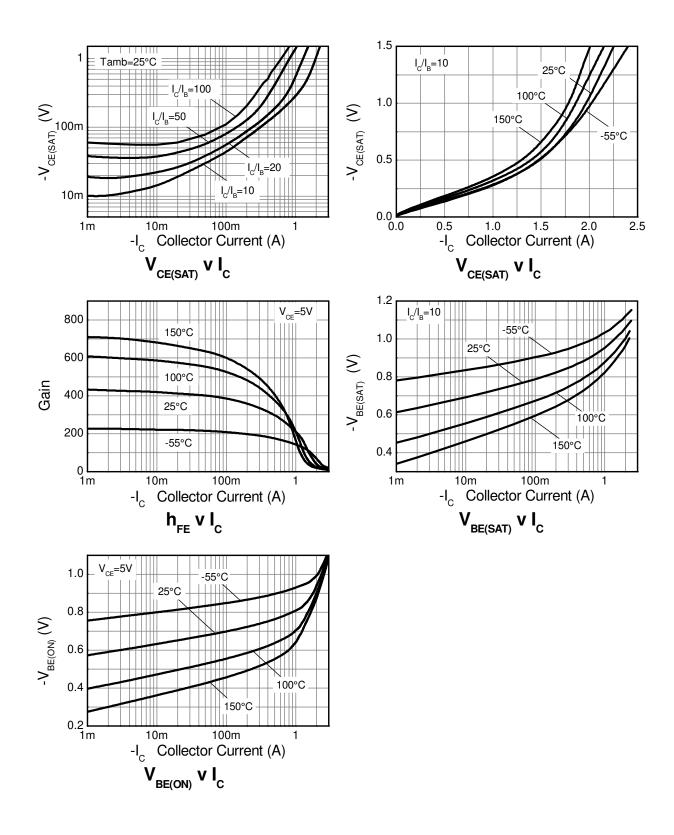
PNP - Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_CBO	-40	-	-	V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	-40	-	-	V	$I_C = -10 \text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	-7	-	-	V	$I_E = -100 \mu A$
Collector Cutoff Current	I _{CBO}	-	-	-100	nA	$V_{CB} = -30V$
Emitter Cutoff Current	I _{EBO}	-	-	-100	. nA	$V_{EB} = -4V$
Collector Emitter Cutoff Current	I _{CES}	-	-	-100	nA	V _{CE} = -30V
Static Forward Current Transfer Ratio (Note 12)	h _{FE}	300 300 250 160	- - -	- 800 - -	-	I _C = -1mA, V _{CE} = -5V I _C = -100mA, V _{CE} = -5V I _C = -500mA, V _{CE} = -5V I _C = -1A, V _{CE} = -5V
		30	-	-		I _C = -2A, V _{CE} = -5V
Collector-Emitter Saturation Voltage (Note 12)	$V_{\text{CE}(\text{sat})}$			-200 -350 -500	mV	$I_C = -0.1A$, $I_B = -1mA$ $I_C = -0.5A$, $I_B = -20mA$ $I_C = -1.0A$, $I_B = -100mA$
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	-	-	-1.0	V	$I_C = -1A$, $V_{CE} = -5V$
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	-	-	-1.1	V	$I_C = -1A$, $I_B = -50mA$
Output Capacitance	C _{obo}	-	-	10	pF	V _{CB} = -10V, f = 1MHz
Transition Frequency	f⊤	150	-	-	MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz

Notes: 12. Measured under pulsed conditions. Pulse width $\leq 300 \mu s$. Duty cycle $\leq 2\%$.



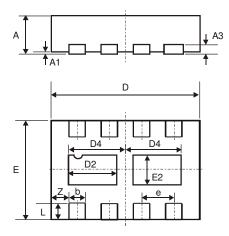
PNP - Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)





Package Outline Dimensions

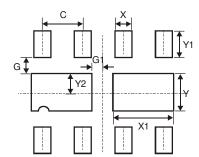
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



W-DFN3020-8						
Туре В						
Dim	Min	Max	Тур			
Α	0.77	0.83	0.80			
A1	0	0.05	0.02			
A3	-	-	0.15			
b	0.25	0.35	0.30			
D	2.95	3.075	3.00			
D2	0.82	1.02	0.92			
D4	1.01	1.21	1.11			
е	ı	1	0.65			
Е	1.95	2.075	2.00			
E2	0.43	0.63	0.53			
L	0.25	0.35	0.30			
Z	-	-	0.375			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.650
G	0.285
G1	0.090
X	0.400
X1	1.120
Υ	0.730
Y1	0.500
Y2	0.365





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